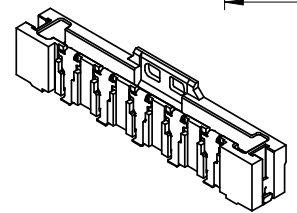
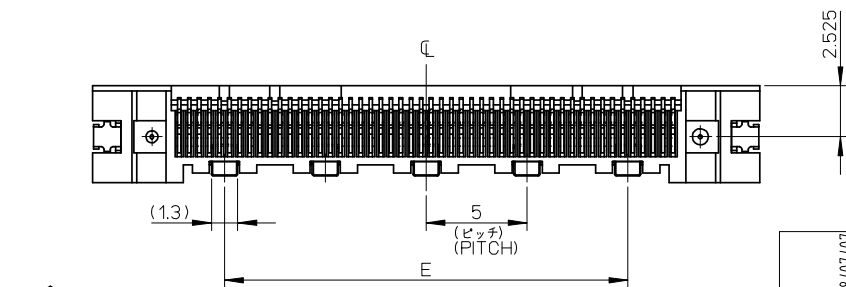
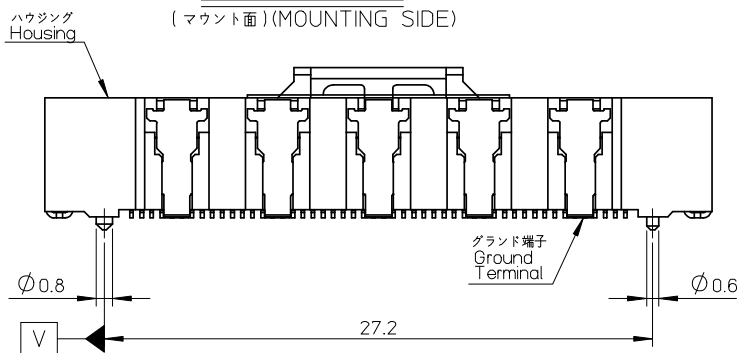
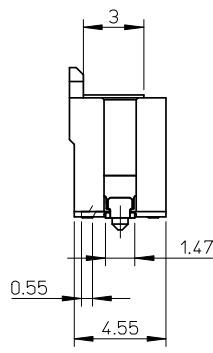
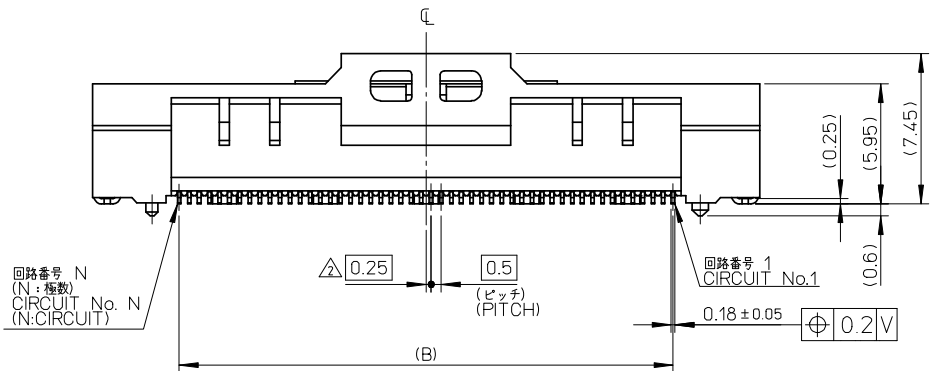


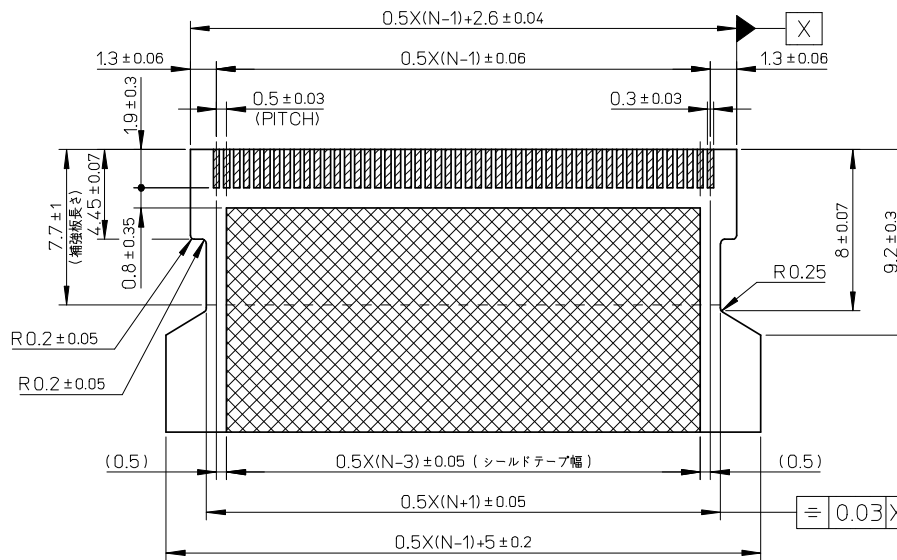
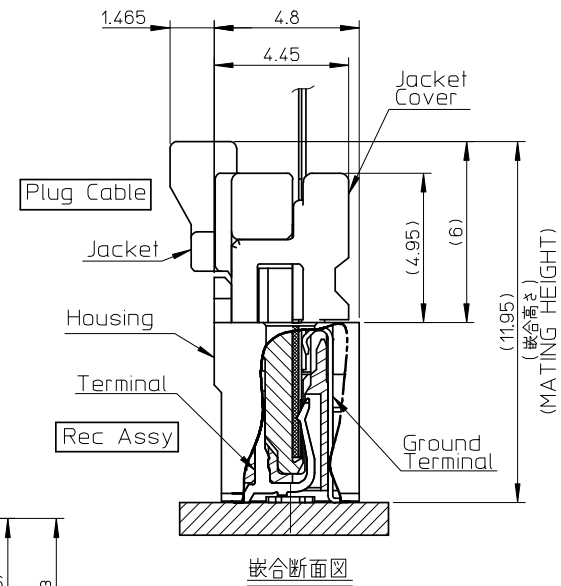
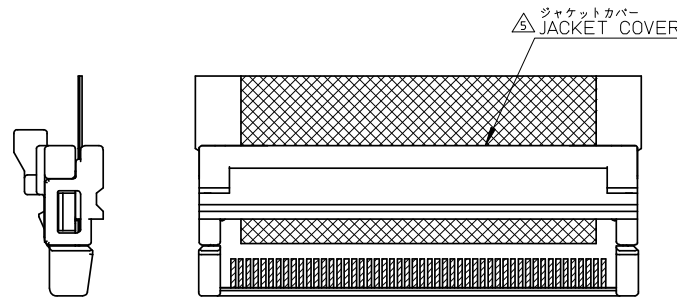
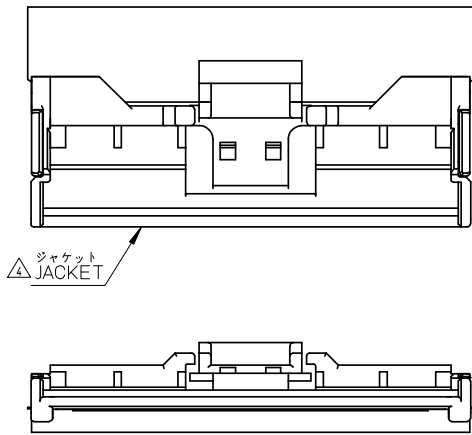
参考基板レイアウト
PC BOARD PATTERN
DIMENSION(REF.)
(マウント面)(MOUNTING SIDE)



5	20	27.2	29.1	24.5	33.1	501786-5081	501786-5051	50
QTY of Term	E	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数
						ORDER No. オーダー番号		

RELEASED EC NO: O	2008/07/07 DRWN:MNABEI	2008/07/09 CHKD:K.MORIKAWA	2008/07/10 APPR:KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER		±0.2	DRAWN BY M.NABEI		DATE '08/07/07		TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY (ST)		
	10 OVER 30 UNDER		±0.25	CHECKED BY K.MORIKAWA		DATE '08/07/07		MOLEX INCORPORATED		
	30 OVER		±0.3	APPROVED BY H.HIRATA		DATE '08/07/07		DOCUMENT NO. SD-501786-010		
ANGULAR		±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SIZE A3		SHEET NO. 1 OF 2	

ELV AND RoHS COMPLIANT.



注記
NOTE

1. 使用材料 MATERIAL

- ハウジング HOUSING : 液晶ポリマー (LCP), ガラス充填, UL94V-0 色: 黒色
LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED,UL94V-0 COLOR:BLACK
- ターミナル TERMINAL : 銅合金(τ=0.18)
COPPER ALLOY(τ=0.18)
- メッキ PLATING : 銅合金(τ=0.18)
COPPER ALLOY(τ=0.18)
- ソルダーテール : ニッケル下地 錫ビスマスメッキ
NICKEL UNDER PLATING, SOLDERABLE
- TAIL AREA : Sn-Bi PLATING OVER NICKEL PLATING
- 金具 FITTING NAIL : 銅合金(τ=0.25)
NICKEL UNDER PLATING, SOLDERABLE
- グラウンド端子 GROUND TERMINAL : 銅合金(τ=0.15)
NICKEL UNDER PLATING, SOLDERABLE

△ N=偶数に適用 (N:極数)
APPLY FOR N-EVEN(N:CIRCUIT)

△ パターン剥離止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.

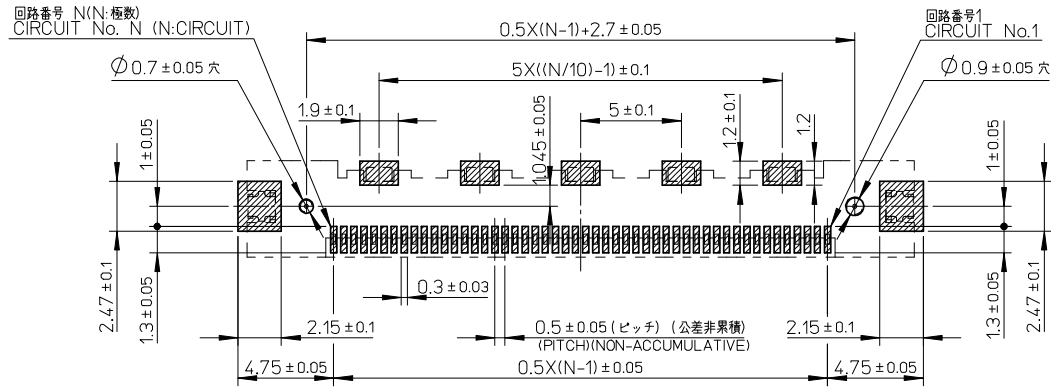
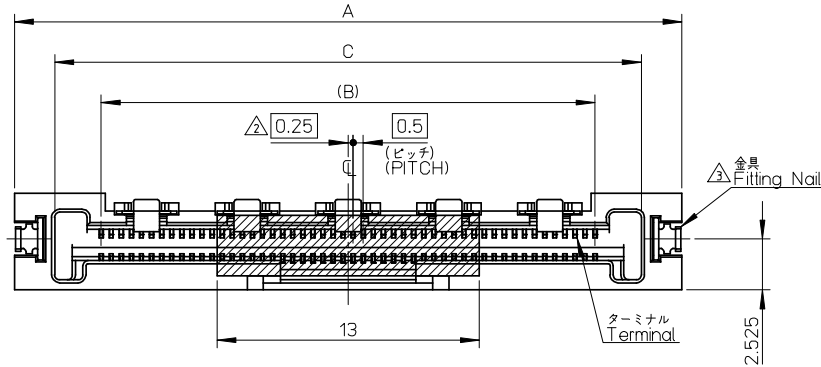
△ 適合ジャケット: 503150-**-09
製品詳細寸法はSD-503150-001を参照下さい。
APPLICABLE JACKET:503150-**-09
RE DETAILED DIMENSION,SEE SD-503150-001.

△ 適合ジャケットカバー: 503151-**-09
製品詳細寸法はSD-503151-001を参照下さい。
APPLICABLE JACKET:503151-**-09
RE DETAILED DIMENSION,SEE SD-503151-001.

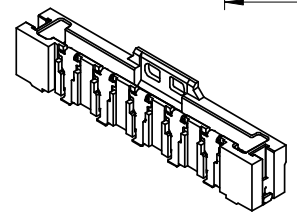
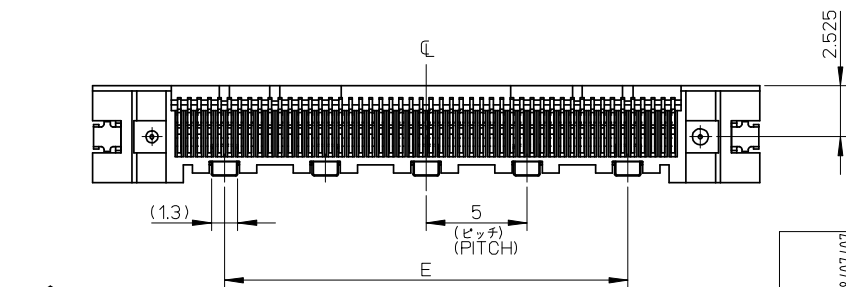
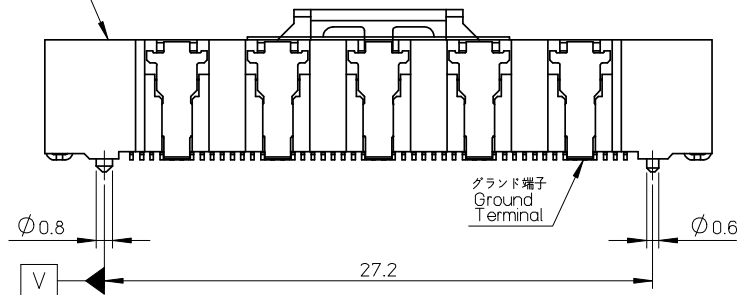
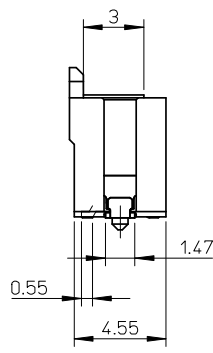
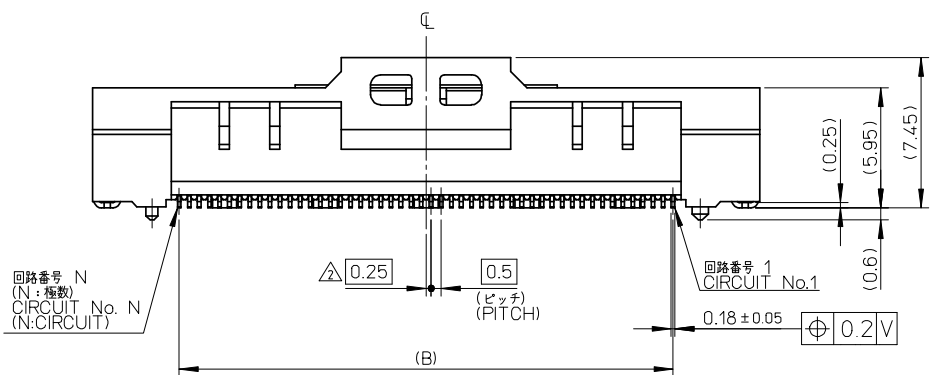
適合FFC推奨寸法
APPLICABLE FFC RECOMMENDED DIMENSION
(仕上がり厚さ: コネクタ接点部 0.3±0.03)
シールド部 0.44±0.05

コネクタ接点部
シールド部

RELEASED EC NO: O	REV	DESCRIPTION DRWN:MNABEI 2008/07/07 CHKD:K.MORIKAWA 2008/07/09 APPR:KMORIKAWA 2008/07/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			10 UNDER	±0.2	DRAWN BY M.NABEI	DATE '08/07/07	TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY (ST)				
			10 OVER 30 UNDER	±0.25	CHECKED BY K.MORIKAWA	DATE '08/07/07	MOLEX INCORPORATED				
			30 OVER	±0.3	APPROVED BY H.HIRATA	DATE '08/07/07					
ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE SHEET 1		MATERIAL NO.	DOCUMENT NO.	SHEET NO. 2 OF 2				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											



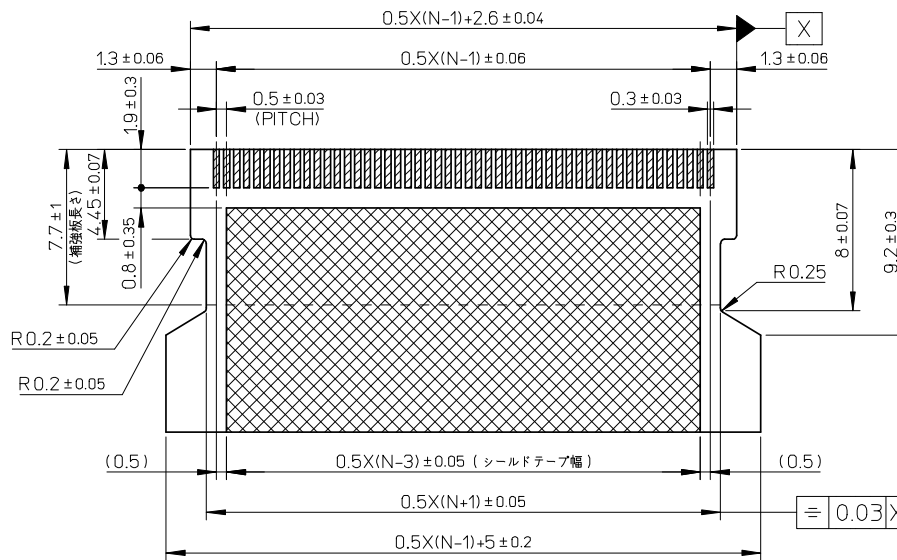
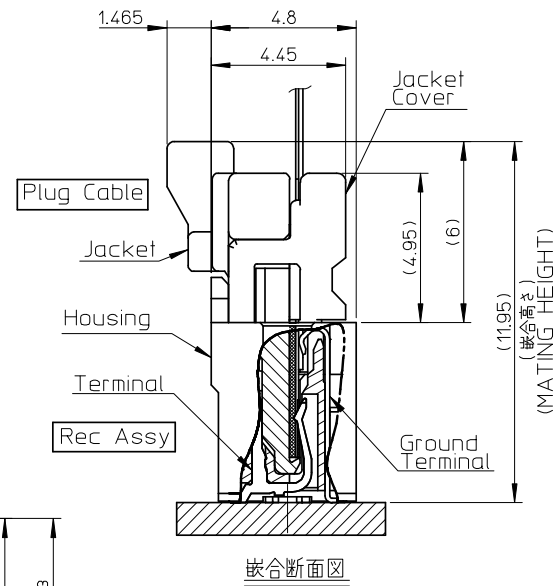
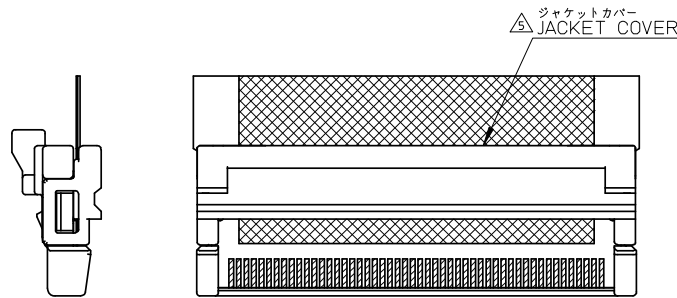
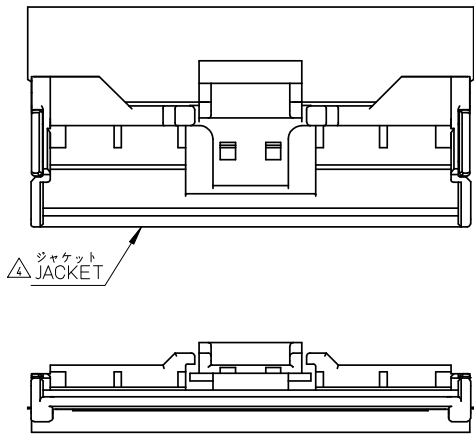
参考基板レイアウト
PC BOARD PATTERN
DIMENSION(REF.)
(マウント面)(MOUNTING SIDE)



5	20	27.2	29.1	24.5	33.1	501786-5081	501786-5051	50
QTY of Term	E	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数
						ORDER No. オーダー番号		

RELEASED EC NO: O	2008/07/07 DRWN:MNABEI	2008/07/09 CHKD:K.MORIKAWA	2008/07/10 APPR:KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER		±0.2	DRAWN BY M.NABEI		DATE '08/07/07		TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY (ST)		
	10 OVER 30 UNDER		±0.25	CHECKED BY K.MORIKAWA		DATE '08/07/07		MOLEX INCORPORATED		
	30 OVER		±0.3	APPROVED BY H.HIRATA		DATE '08/07/07		DOCUMENT NO. SD-501786-010		
ANGULAR ±1 °				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SHEET NO. 1 OF 2		
SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

ELV AND RoHS COMPLIANT.



適合FFC推奨寸法
 APPLICABLE FFC
 RECOMMENDED DIMENSION
 (仕上がり厚さ: コネクタ接点部 0.3±0.03)
 シールド部 0.44±0.05

コネクタ接点部
 シールド部

注記
 NOTE

1. 使用材料 MATERIAL

- ハウジング HOUSING : 液晶ポリマー (LCP), ガラス充填, UL94V-0 色: 黒色
 LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED,UL94V-0 COLOR:BLACK
- ターミナル TERMINAL : 銅合金(τ=0.18)
 COPPER ALLOY(τ=0.18)
- メッキ PLATING : 銅合金(τ=0.18)
 COPPER ALLOY(τ=0.18)
- ソルダーテール : ニッケル下地 錫ビスマスメッキ
 NICKEL UNDER PLATING, SOLDERABLE
- TAIL AREA : Sn-Bi PLATING OVER NICKEL PLATING
- 金具 FITTING NAIL : 銅合金(τ=0.25)
 ニッケル下地 錫メッキ
 COPPER ALLOY(τ=0.25), TIN OVER NICKEL PLATING.
- グラウンド端子 GROUND TERMINAL : 銅合金(τ=0.15)
 ニッケル下地 錫メッキ
 COPPER ALLOY(τ=0.15), TIN OVER NICKEL PLATING.

- ④ N=偶数に適用 (N:極数)
 APPLY FOR N-EVEN(N:CIRCUIT)
- ③ パターン剥離止め用金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.
- ④ 適合ジャケット: 503150-**-09
 製品詳細寸法はSD-503150-001を参照下さい。
 APPLICABLE JACKET:503150-**-09
 RE DETAILED DIMENSION,SEE SD-503150-001.
- ⑤ 適合ジャケットカバー: 503151-**-09
 製品詳細寸法はSD-503151-001を参照下さい。
 APPLICABLE JACKET:503151-**-09
 RE DETAILED DIMENSION,SEE SD-503151-001.

RELEASED EC NO: O	REV	DESCRIPTION DRWN:MNABEI 2008/07/07 CHKD:K.MORIKAWA 2008/07/09 APPR:KMORIKAWA 2008/07/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			10 UNDER	±0.2	DRAWN BY M.NABEI	DATE '08/07/07	TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY (ST)			
			10 OVER 30 UNDER	±0.25	CHECKED BY K.MORIKAWA	DATE '08/07/07	MOLEX INCORPORATED			
			30 OVER	±0.3	APPROVED BY H.HIRATA	DATE '08/07/07				
ANGULAR ±1 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-501786-010	SHEET NO. 2 OF 2		
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										

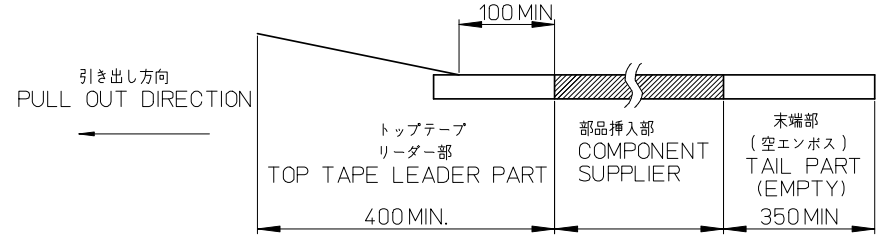
ELV AND RoHS COMPLIANT.

NOTES

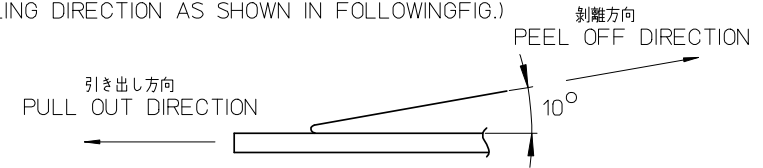
1. 梱包数量：900 個/リール
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH

トップテープ接着部
TOP TAPE BONDED PART
(空エンボス)
(EMPTY)

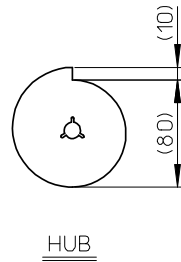
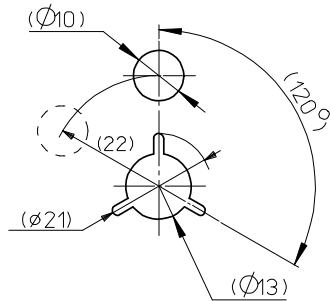
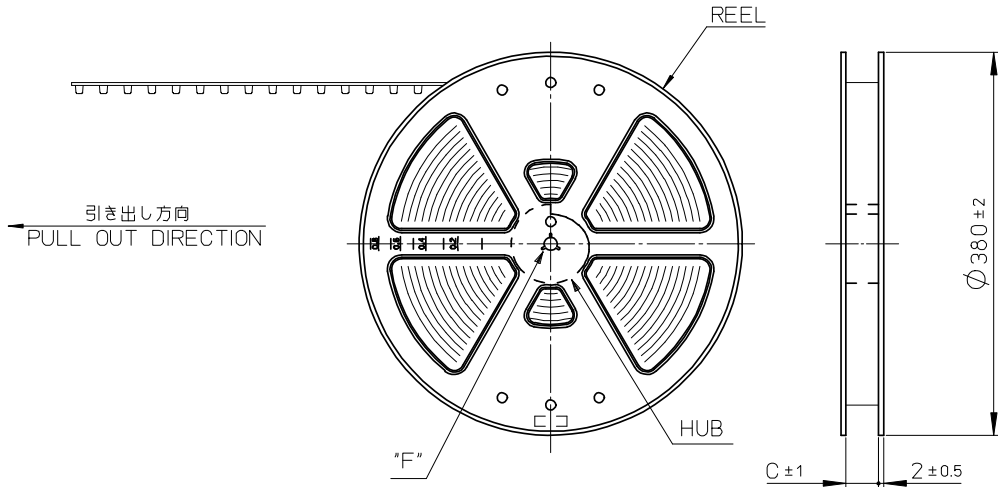
トップテープ未接着部
TOP TAPE NON-BONDED PART



3. トップテープの剥離強度：「JES-59」参照のこと
(剥離方向は下図参照)
PEEL-OFF FORCE OF TOP TAPE : REFER TO JES-59
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)



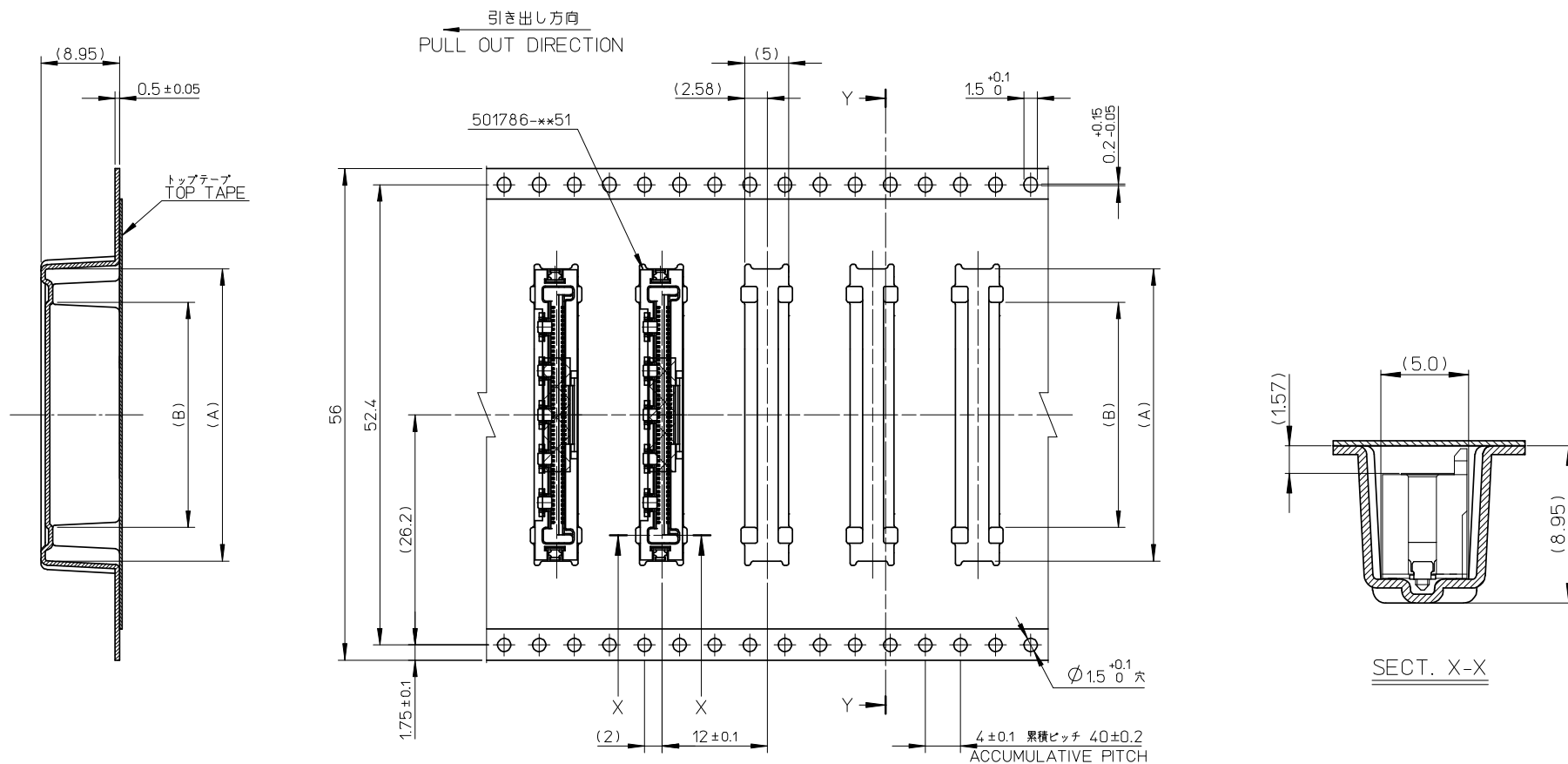
4. 製品詳細寸法については図面 SD-501786-010を参照下さい。
RE DETAILED DIMENSION, SEE SD-501786-010.
5. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE) : ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE) : PET, PE, PE
リール(REEL) : ポリスチレン(POLYSTYRENE) <<<リサイクル材を含む>>>
<<<RECYCLE MATERIAL CONTAINED>>>



501786-**81 MODEL NO.

RELEASED EC NO: 0	2008/07/08 DRWN:MNABEI	2008/07/09 CHKD:K.MORIKAWA	2008/07/10 APPR:KMORIKAWA	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER ±0.2		DRAWN BY M.NABEI		DATE '08/07/08	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE					
	10 OVER 30 UNDER ±0.25		CHECKED BY K.MORIKAWA		DATE '08/07/08	MOLEX INCORPORATED					
	30 OVER ±0.3		APPROVED BY H.HIRATA		DATE '08/07/08	DOCUMENT NO. SD-501786-011					
ANGULAR ±3°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 2		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

ELV AND RoHS COMPLIANT.



56mm幅キャリアテープ
56mm WIDTH CARRIER TAPE

56	57.4	25.68	33.3	501786-5081	50
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	製品番号 MATERIAL NO.	極数 CKT

RELEASED EC NO: 0 DRWN: MABEI 2008/07/08 CHK'D: MORIKAWA 2008/07/09 APPR: KMORIKAWA 2008/07/10	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		ANGULAR ±3° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY M. NABEI	DATE '08/07/08	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE		
		SEE TABLE	CHECKED BY K. MORIKAWA	DATE '08/07/08	MOLEX INCORPORATED		
		SIZE A3	APPROVED BY H. HIRATA	DATE '08/07/08	DOCUMENT NO. SD-501786-011	SHEET NO. 2 OF 2	

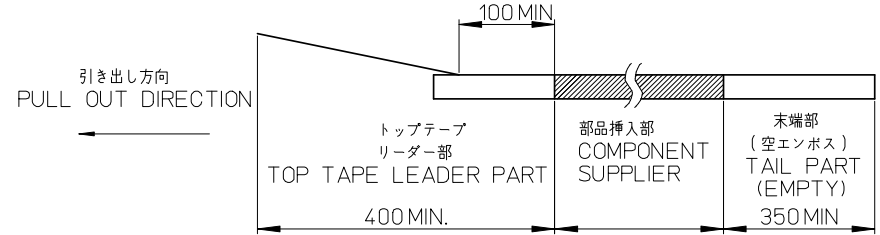
ELV AND RoHS COMPLIANT.

NOTES

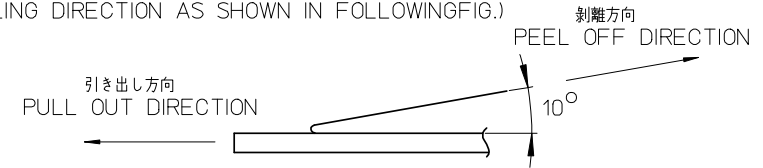
1. 梱包数量：900 個/リール
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH

トップテープ接着部
TOP TAPE BONDED PART
(空エンボス)
(EMPTY)

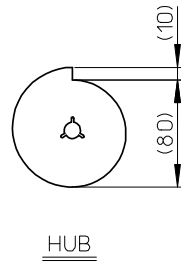
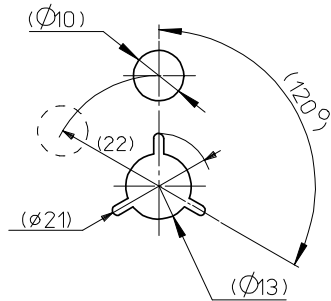
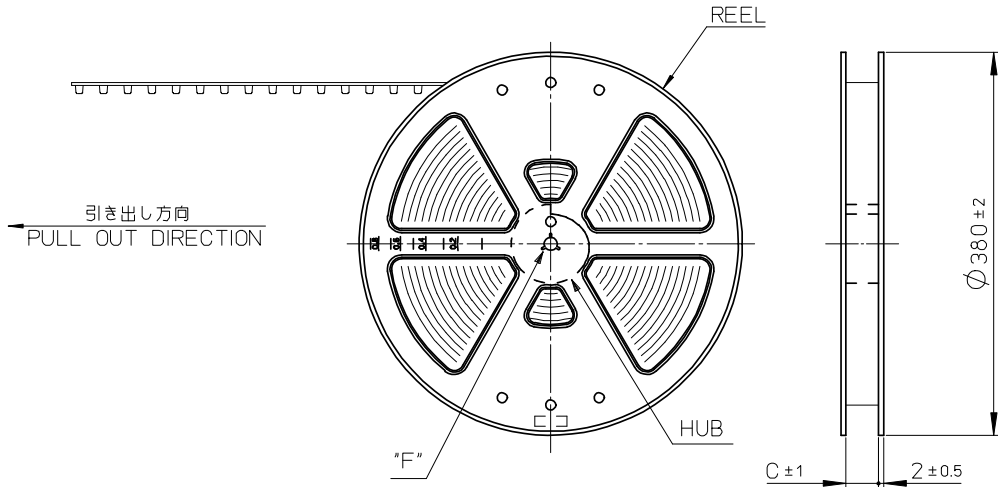
トップテープ未接着部
TOP TAPE NON-BONDED PART



3. トップテープの剥離強度：「JES-59」参照のこと
(剥離方向は下図参照)
PEEL-OFF FORCE OF TOP TAPE : REFER TO JES-59
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)



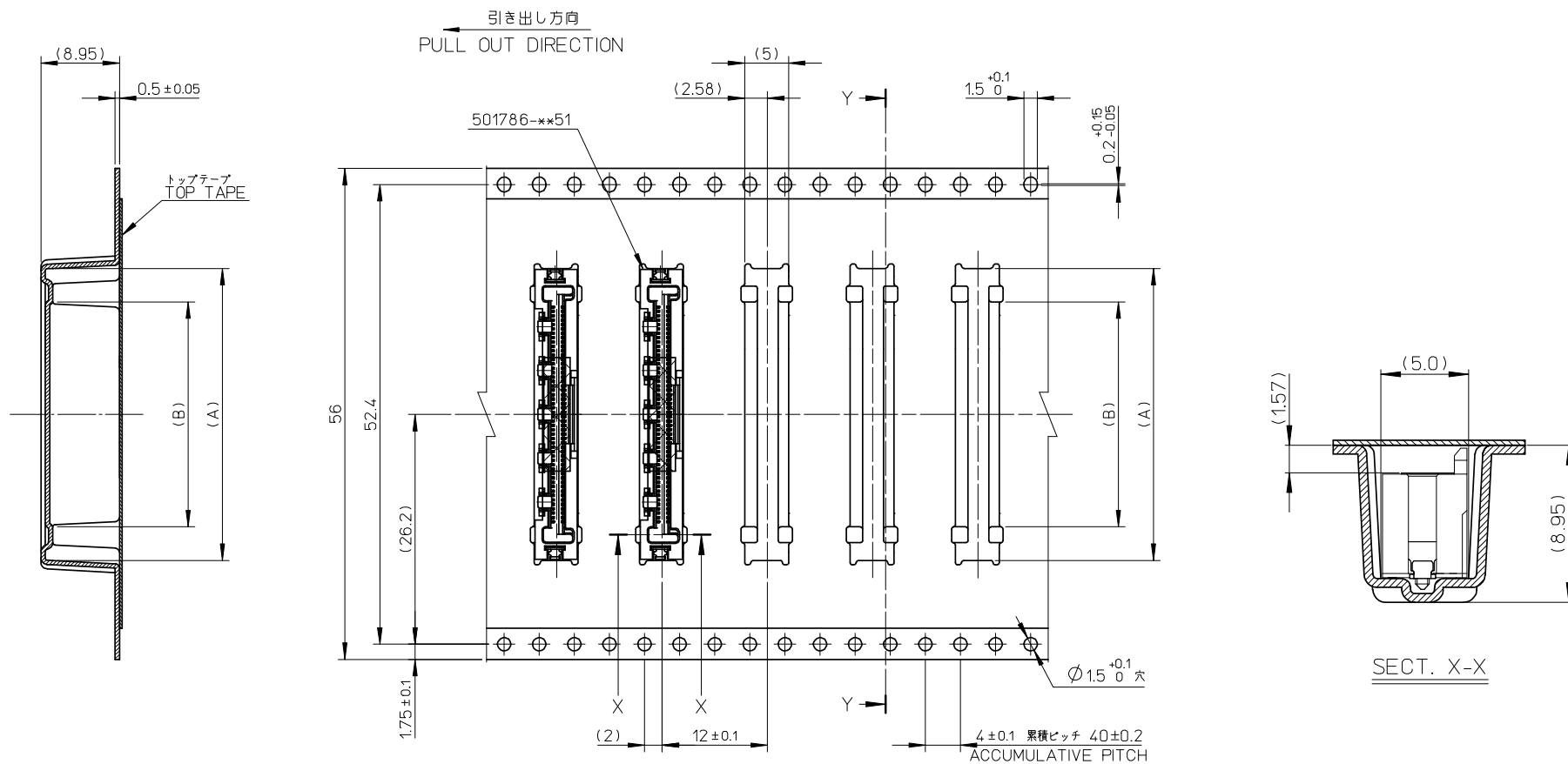
4. 製品詳細寸法については図面 SD-501786-010を参照下さい。
RE DETAILED DIMENSION, SEE SD-501786-010.
5. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE) : ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE) : PET, PE, PE
リール(REEL) : ポリスチレン(POLYSTYRENE) <<>リサイクル材を含む<>>
<<>RECYCLE MATERIAL CONTAINED<>>



501786-**81 MODEL NO.

RELEASED EC NO: 0	2008/07/08 DRWN:MNABEI	2008/07/09 CHKD:K.MORIKAWA	2008/07/10 APPR:KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
				10 UNDER ± 0.2	DRAWN BY M.NABEI	DATE '08/07/08	TITLE	EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE MOLEX INCORPORATED
				10 OVER 30 UNDER ± 0.25	CHECKED BY K.MORIKAWA	DATE '08/07/08		
				30 OVER ± 0.3	APPROVED BY H.HIRATA	DATE '08/07/08		
			ANGULAR ± 3 °	MATERIAL NO. SEE SHEET 2	DOCUMENT NO. SD-501786-011	SHEET NO. 1 OF 2		
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

ELV AND RoHS COMPLIANT.



56mm幅キャリアテープ
56mm WIDTH CARRIER TAPE

56	57.4	25.68	33.3	501786-5081	50
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	製品番号 MATERIAL NO.	極数 CKT

RELEASED EC NO: 0 DRWN: MABEI 2008/07/08 CHKDK: MORIKAWA 2008/07/09 APPR: KMORIKAWA 2008/07/10	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		ANGULAR ±3° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWN BY M. NABEI	DATE '08/07/08	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE		
		SEE TABLE	CHECKED BY K. MORIKAWA	DATE '08/07/08	MOLEX INCORPORATED		
		SIZE A3	APPROVED BY H. HIRATA	DATE '08/07/08	DOCUMENT NO. SD-501786-011	SHEET NO. 2 OF 2	